



## RoHS Implementation Strategy

The rate of conversion of F5 Networks RoHS compliant assembly processes will be customer driven. As an industry leader in network appliance products, we have assessed and documented the requirements necessary to make the conversion and successfully implemented a RoHS compliant assembly processes in production in July 2006.

F5 produces RoHS compliant products that fall under one or more technical exemptions for lead (Pb) and cadmium listed in the EU Directive 2002/95/EC Annex. These exemptions include:

1. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
2. Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85% lead).
3. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages.
4. Lead in solder consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
5. Lead as an alloying element in steel containing up to 0.35% lead by weight, aluminum containing up to 0.4% lead by weight and as a copper alloy containing up to 4% lead by weight (i.e. screws).
6. Lead used in compliant pin connector systems (i.e. connectors).
7. Lead and cadmium in optical and filter glass.
8. Lead in electronic ceramic parts (e.g. piezoelectronic devices).